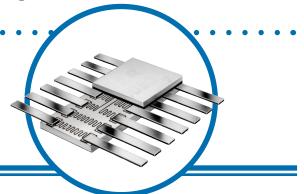
Space Flight Surface Mount Flat Packs Resistor Networks



8900 Space Series

- 100% screened to NASA EEE-INST-002 Level 1
- Gold to gold bonded lead construction no internal solder connections or wire bonds
- Excellent passive solution for space flight hardware
- Self Passivating TaNFilm® element with superior moisture performance



The 8900 Space Series features our TaNFilm® Flat Pack Network superior moisture performance of tantalum nitride resistor film system. Rugged, welded lead construction eliminates fragile wire bond construction and provides superior surface mount reliability. These parts are screened per MIL-PRF-83401 then upgraded to the stringent screening requirements for NASA space flight requirements.

Electrical Data

	Range	Available Absolute Tolerances	Available Ratio Tolerance (reference R1)	Available Absolute TCR (ppm/°C)	Tracking TCR (reference to R1) (ppm/°C)	MIL-PRF-83401 Ratings	
Package						Voltage (not to exceed √P x R)	Element Power Rating 70°C
Isolated Schematic	20Ω - 99Ω	FGJ	FGJ	±100	±10	50V	50mW
	100Ω - 121ΚΩ	BFGJ	ABFG	±25, ±50, ±100	±5	50 V	
Bussed Schematic	20Ω - 499Ω	FGJ	FGJ	±100	±20	501/	25mW
	500.0Ω - 100ΚΩ	BFGJ	ABFG	±25, ±50, ±100	±5	50V	

Screening Data

Series Type	Precap per MIL-STD-883	Optional Precap Source Verification	Screening per MIL-PRF-83401	Addition Screening IAW EEE-INST-002 Level 1					
				Serialized	Thermal Shock 25 Cycles	Power Conditioning 100 Hours	Optional Final Source Inspection	Marking P/N	
89xxSQ	Yes	Yes	Yes	Yes	Yes	Yes	Yes	89xxSQ -xx-yyyyzz	



IRC reserves the right to make changes in product specification without notice or liability.

All information is subject to IRC's own data and is considered accurate at time of going to print.





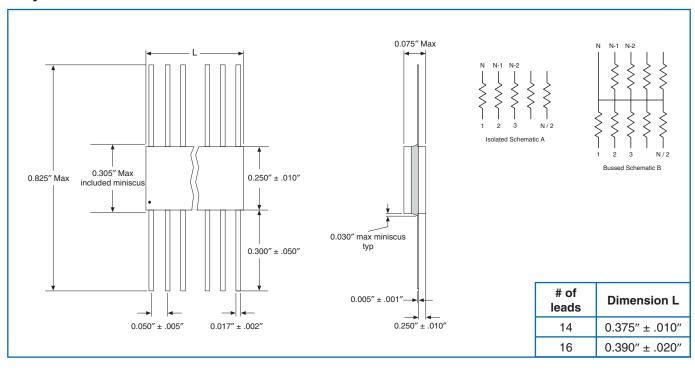
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Environmental Data

Environnmental Test	Maximum ∆R per	Performance		
MIL-PRF-83401	Characteristic H	Typical	Maximum	
Thermal Shock and Power Conditioning	±0.50%	±0.02%	±0.10%	
Low Temperature Operation	±0.10%	±0.01%	±0.01%	
Short Time Overload	±0.10%	±0.01%	±0.05%	
High Temperature Exposure	±0.20%	±0.03%	±0.10%	
Effects of Solder	±0.10%	±0.02%	±0.10%	
Moisture Resistance	±0.40%	±0.03%	±0.10%	
Life	±0.50%	±0.03%	±0.10%	

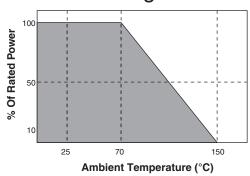
Physical and Schematic Data



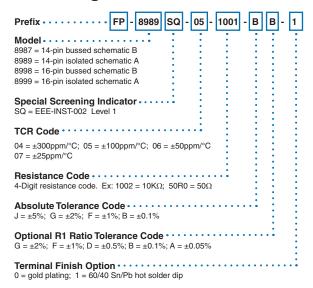
Space Flight Surface Mount Flat Packs Resistor Networks



Power Derating Curve



Ordering Data



For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.